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20. (Amended) A method of producing a crystalline substrate based device comprising:

providing a microstructure on a substrate;

providing a spacer onto said substrate, said spacer defining at least one cavity extending entirely therethrough; and

B1

adhesively sealing at least one transparent packaging layer onto said spacer over said microstructure and at least partially spaced therefrom, thereby to define a gap at said at least one cavity between said microstructure and said at least one packaging layer, wherein said spacer is formed as a piece separate from said substrate and from said at least one packaging layer.

REMARKS

Applicant has carefully studied the outstanding Official Action. The present response is intended to be fully responsive to all points of rejection raised by the Examiner and is believed to place the application in condition for allowance. Favorable reconsideration and allowance of the application is respectfully requested.

Claim 26 stands rejected under 35 U.S.C. § 112, second paragraph, because of a missing antecedent for "said at least one cavity". Claim 20, from which claim 26 depends, ahs been amended to provide the missing antecedent.

Claims 20-23, 25-29 and 34 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Salatino et al. (US. Patent No. 5,915,168). Clams 24, 33 and 36 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Salatino as applied to claims 20-23, 25-29 and 34 above, and further in view of Ichikawa et al. (U.S. Patent No. 5,996,199).